

EXHIBIT J



IC Interconnect
An ISO/TS 16949:2002 and ISO 9001:2000
Registered Company

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Request for Quote

IC Interconnect offers a wide range of services to meet customer needs. In order that ICI might provide the most comprehensive response please fill out this RFQ with as much information as possible. ICI's engineering staff will assess your requirements and evaluate them against our technology offerings in terms of process parameters and design rules. The sales staff will then be in a position to provide a budgetary quote for you to work with. In the event that this level of detail is premature, please feel free to contact us by phone or e-mail to discuss your application.

Contact Name: [REDACTED]

Company Name: [REDACTED]

Company Address: [REDACTED]
[REDACTED]

Phone: [REDACTED]

Fax: [REDACTED]

Email: [REDACTED]

Device Name: [REDACTED]

Services Requested: (select)

- 1. Ni/Au UBM + Solder Bumping (Flip Chip) (please fill out sections A through D)
- 2. Ni/Au UBM + Ball Placement (WLCSP) (please fill out sections A through D)
- 3. Ni/Au as a wire bond surface (please fill out sections A through C)
- 4. Ni/Au as a hard mini bump (please fill out sections A through C)
- 5. Solder Deposition on your UBM (please fill out sections A, B and D)
- 6. Reliability Modeling (submit, you will be contacted for details)
- 7. Laser Mark (please fill out sections A, B and E)
- 8. Flip Chip Assembly (submit, you will be contacted for details)

Preliminary available RFQ's

A. Program Information

Application Description:

Files Available (select all that apply)

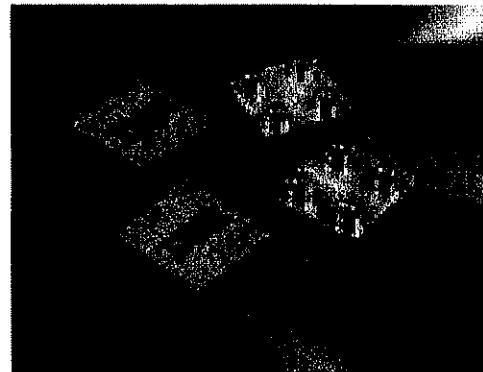
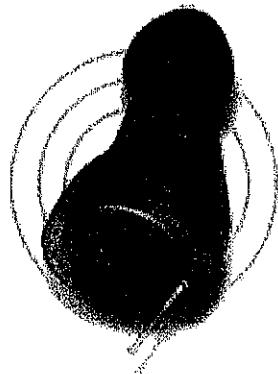
- GDSII
- Wafer Map
- Specifications

Program Status (select)

- In production Wafer Volume wafers/week
- Design in qualification Wafer Volume Forecast wafers/week
- Die design complete and taped out
- Die function defined not yet taped out
- R&D

Timing (select)

- Immediate
- Within the next three to six months
- Within the next six months to a year



B. General Wafer Information

Wafer Type (select)

- Silicon
- GaAs
- SiGe
- Lithium Based
- Glass
- Quartz
- Ceramic
- Other

[Redacted]

Wafer Dimensions

Thickness
Diameter

[Redacted] micron
[Redacted] mm

Final Grind Condition (select)

- Full thickness
- Mechanical grind
- Chem or Plasma

Passivation Type (select)

- Silicon Nitride
- Silicon Oxide
- Silicon OxyNitride
- Polyimide
- BCB
- Other

[Redacted]

Passivation

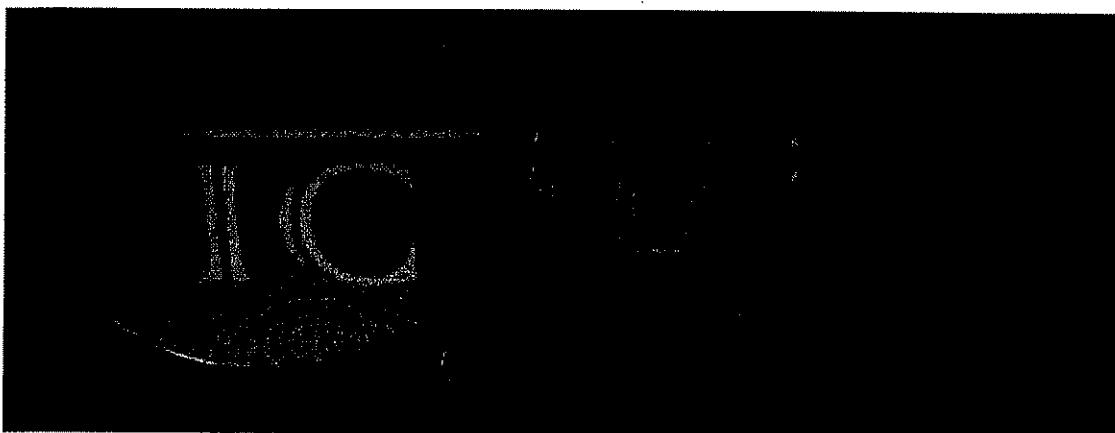
Thickness

[Redacted] micron

Backside Condition (select)

- Oxide
- Si
- Polymer
- Ag
- Au
- Other

[Redacted]



C. Ni/Au Plating Related Information

Pad Metal Composition (select)

- Aluminum %Al %Si %Cu
 Copper
 Other

Pad Metal Thickness $t =$ micron, \pm micron

Passivation Opening Size and Shape (select)

- Round dia= micron
 Rectangle x= micron, y= micron
 Other

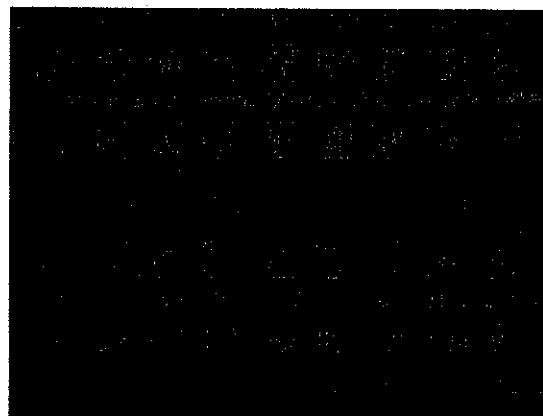
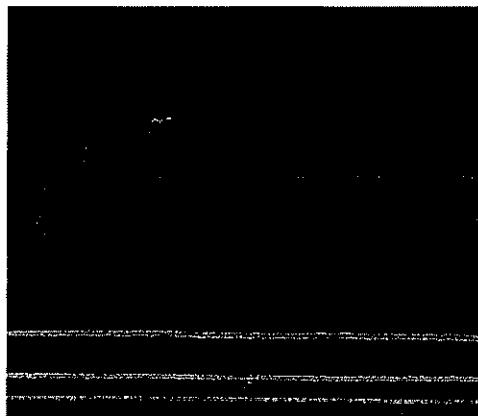
Open Metal (other than pads to be bumped)

- in the Streets yes no
in the Die yes no
open Fuses yes no

Wafer contains Ink Dots yes no

Desired Ni Thickness $t =$ micron

Minimum Spacing between open Metal (edge to edge) micron



D. Solder Related Information

Bond Pad Layout: (select)

- Full Area Array
- Peripheral (1 row)
- Peripheral (2 rows)
- Other

Solder Alloy

- 63Sn/37Pb
- 90Pb/10Sn
- 95.5Sn/3.8Ag/0.7Cu
- Other

Minimum Pitch within a Die (centerline to centerline) micron

Minimum Pitch Die to Die (centerline to centerline) micron

Minimum Distance from Pad edge to Die edge micron

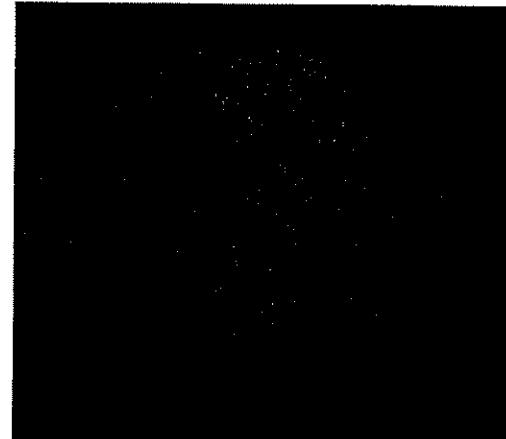
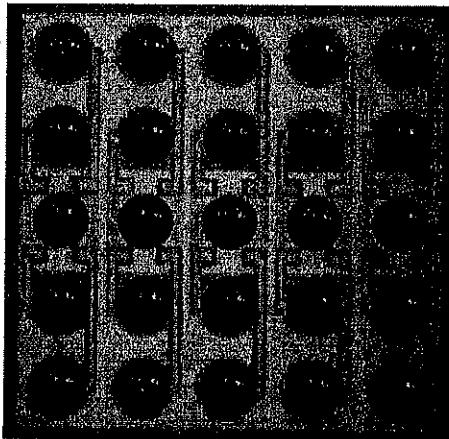
Die Stepping Distance x= micron y= micron

Saw Street Width micron

Solderable Metal Size and Shape:

- Round dia= micron
- Rectangle x= micron, y= micron
- Other

Desired Solder Bump Height micron



E. Laser Mark Related Information

Mark Color: (select)

- Light
- Dark

Number of Die per wafer

Die Size x= micron y= micron

Number of Characters per Die

